

REPETITIVE AVALANCHE AND dv/dt RATED HEXFET® TRANSISTOR

IRHI7460SE

N-CHANNEL SINGLE EVENT EFFECT (SEE) RAD HARD

500 Volt, 0.32 Ω , (SEE) RAD HARD HEXFET

International Rectifier's (SEE) RAD HARD technology HEXFETs demonstrate virtual immunity to SEE failure. Additionally, under **identical** pre- and post-radiation test conditions, International Rectifier's RAD HARD HEXFETs retain **identical** electrical specifications up to 1×10^5 Rads (Si) total dose. No compensation in gate drive circuitry is required. These devices are also capable of surviving transient ionization pulses as high as 1×10^{12} Rads (Si)/Sec, and return to normal operation within a few microseconds. Since the SEE process utilizes International Rectifier's patented HEXFET technology, the user can expect the highest quality and reliability in the industry.

RAD HARD HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and temperature stability of the electrical parameters.

They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers and high-energy pulse circuits in space and weapons environments.

Product Summary

Part Number	BV _{DSS}	R _{DS(on)}	I _D
IRHI7460SE	500V	0.32 Ω	20A

Features:

- Radiation Hardened up to 1×10^5 Rads (Si)
- Single Event Burnout (SEB) Hardened
- Single Event Gate Rupture (SEGR) Hardened
- Gamma Dot (Flash X-Ray) Hardened
- Neutron Tolerant
- Identical Pre- and Post-Electrical Test Conditions
- Repetitive Avalanche Rating
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Electrically Isolated
- Ceramic Eyelets

Absolute Maximum Ratings

Pre-Radiation

	Parameter	IRHI7460SE	Units
I _D @ V _{GS} = 12V, T _C = 25°C	Continuous Drain Current	20	A
I _D @ V _{GS} = 12V, T _C = 100°C	Continuous Drain Current	12	
I _{DM}	Pulsed Drain Current ①	80	
P _D @ T _C = 25°C	Max. Power Dissipation	300	W
	Linear Derating Factor	2.4	W/K ⑤
V _{GS}	Gate-to-Source Voltage	±20	V
E _{AS}	Single Pulse Avalanche Energy ②	500	mJ
I _{AR}	Avalanche Current ①	20	A
E _{AR}	Repetitive Avalanche Energy ①	30	mJ
dv/dt	Peak Diode Recovery dv/dt ③	3.5	V/ns
T _J	Operating Junction	-55 to 150	°C
T _{STG}	Storage Temperature Range		
	Lead Temperature	300 (0.063 in. (1.6mm) from case for 10 sec.)	
	Weight	10.9 (typical)	g

Electrical Characteristics @ T_j = 25°C (Unless Otherwise Specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV _{DSS}	Drain-to-Source Breakdown Voltage	500	—	—	V	V _{GS} = 0V, I _D = 1.0 mA
ΔBV _{DSS} /ΔT _j	Temperature Coefficient of Breakdown Voltage	—	0.68	—	V/°C	Reference to 25°C, I _D = 1.0 mA
RDS(on)	Static Drain-to-Source	—	—	0.32	Ω	V _{GS} = 12V, I _D = 12A ④
	On-State Resistance	—	—	0.36		V _{GS} = 12V, I _D = 20A
VGS(th)	Gate Threshold Voltage	2.5	—	4.5	V	V _{DS} = V _{GS} , I _D = 1.0 mA
gfs	Forward Transconductance	3.5	—	—	S (Ω)	V _{DS} > 15V, I _{DS} = 12A ④
IDSS	Zero Gate Voltage Drain Current	—	—	50	μA	V _{DS} = 0.8 x Max Rating, V _{GS} = 0V
		—	—	250		V _{DS} = 0.8 x Max Rating V _{GS} = 0V, T _j = 125°C
IGSS	Gate-to-Source Leakage Forward	—	—	100	nA	V _{GS} = 20V
IGSS	Gate-to-Source Leakage Reverse	—	—	-100		V _{GS} = -20V
Qg	Total Gate Charge	—	—	260	nC	V _{GS} = 12V, I _D = 20A V _{DS} = Max. Rating x 0.5
Qgs	Gate-to-Source Charge	—	—	40		
Qgd	Gate-to-Drain ("Miller") Charge	—	—	200		
td(on)	Turn-On Delay Time	—	—	45	ns	V _{DD} = 250V, I _D = 20A, R _G = 2.35Ω
tr	Rise Time	—	—	140		
td(off)	Turn-Off Delay Time	—	—	140		
tf	Fall Time	—	—	110		
LD	Internal Drain Inductance	—	8.7	—	nH	Measured from the drain lead, 6mm (0.25 in.) from package to center of die.
LS	Internal Source Inductance	—	8.7	—		Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad.
Ciss	Input Capacitance	—	6400	—	pF	V _{GS} = 0V, V _{DS} = 25V f = 1.0 MHz
Coss	Output Capacitance	—	1100	—		
Crss	Reverse Transfer Capacitance	—	375	—		

Source-Drain Diode Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)	—	—	20	A	Modified MOSFET symbol showing the integral reverse p-n junction rectifier. 
I _{SM}	Pulse Source Current (Body Diode) ①	—	—	80		
V _{SD}	Diode Forward Voltage	—	—	1.8	V	T _J = 25°C, I _S = 20A, V _{GS} = 0V ④
t _{rr}	Reverse Recovery Time	—	—	1200	ns	T _J = 25°C, I _F = 20A, di/dt ≤ 100A/μs V _{DD} ≤ 50V ④
Q _{RR}	Reverse Recovery Charge	—	—	16	μC	
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L _S + L _D .				

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
RthJC	Junction-to-Case	—	—	0.42	K/W⑤	
RthJA	Junction-to-Ambient	—	—	30		
RthCS	Case-to-Sink	—	0.21	—		Typical socket mount

Radiation Performance of Rad Hard HEXFETs

International Rectifier Radiation Hardened HEXFETs are tested to verify their hardness capability. The hardness assurance program at International Rectifier uses two radiation environments.

Every manufacturing lot is tested in a low dose rate (total dose) environment per MIL-STD-750, test method 1019. International Rectifier has imposed a standard gate voltage of 12 volts per note 6 and a V_{DSS} bias condition equal to 80% of the device rated voltage per note 7. Pre- and post-radiation limits of the devices irradiated to 1×10^5 Rads (Si) are identical and are presented in Table 1. The values in Table 1 will be met for either of the two low dose rate test circuits that are used.

Both pre- and post-radiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison. It should be noted that at a radiation level of 1×10^5 Rads (Si), no change in limits are specified in DC parameters.

High dose rate testing may be done on a special request basis, using a dose rate up to 1×10^{12} Rads (Si)/Sec.

International Rectifier radiation hardened HEXFETs have been characterized in neutron and heavy ion Single Event Effects (SEE) environments. Single Event Effects characterization is shown in Table 3.

Table 1. Low Dose Rate ⑥ ⑦

Table 1. Low Dose Rate ⑥ ⑦		IRHI7460SE			
Parameter		100K Rads (Si)		Units	Test Conditions ⑩
		min.	max.		
BV _{DSS}	Drain-to-Source Breakdown Voltage	500	—	V	V _{GS} = 0V, I _D = 1.0 mA
V _{GS(th)}	Gate Threshold Voltage ④	2.5	4.5		V _{GS} = V _{DS} , I _D = 1.0 mA
I _{GSS}	Gate-to-Source Leakage Forward	—	100	nA	V _{GS} = 20V
I _{GSS}	Gate-to-Source Leakage Reverse	—	-100		V _{GS} = -20V
I _{DSS}	Zero Gate Voltage Drain Current	—	50	μA	V _{DS} = 0.8 x Max Rating, V _{GS} = 0V
R _{DS(on)1}	Static Drain-to-Source ④ On-State Resistance One	—	0.32	Ω	V _{GS} = 12V, I _D = 12A
V _{SD}	Diode Forward Voltage ④	—	1.8	V	T _C = 25°C, I _S = 20A, V _{GS} = 0V

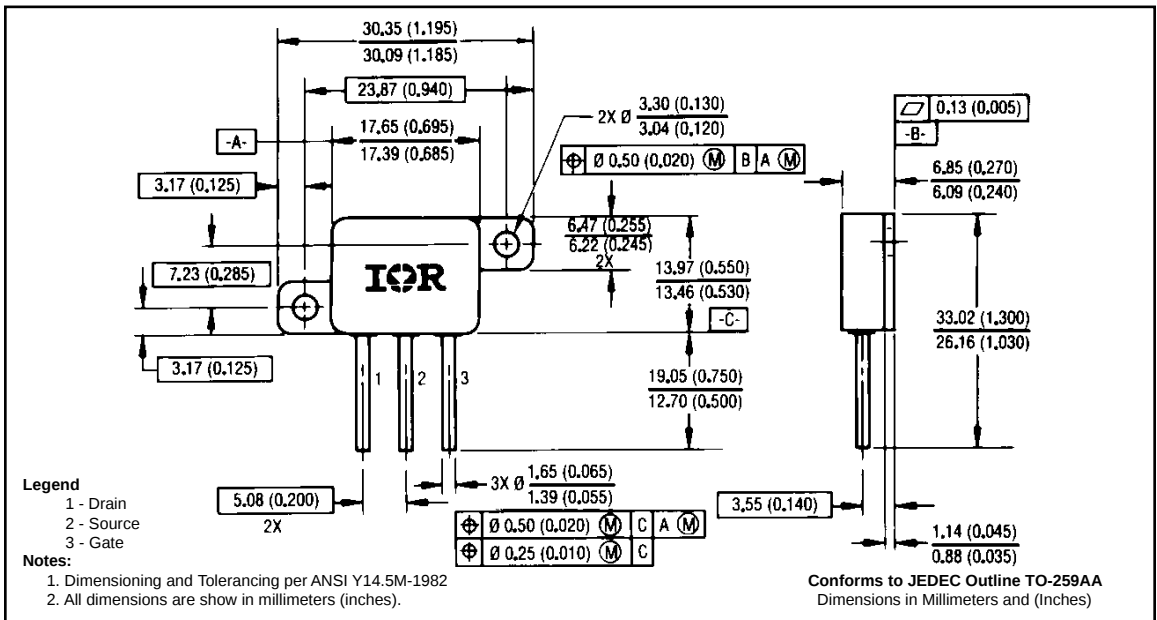
Table 2. High Dose Rate ⑧

Parameter		10 ¹¹ Rads (Si)/sec			10 ¹² Rads (Si)/sec			Units	Test Conditions
		Min.	Typ	Max.	Min.	Typ.	Max.		
V_{DSS}	Drain-to-Source Voltage	—	—	400	—	—	400	V	Applied drain-to-source voltage during gamma-dot
I_{PP}		—	7	—	—	7	—	A	Peak radiation induced photo-current
di/dt		—	16	—	—	2.3	—	A/ μ sec	Rate of rise of photo-current
L_1		—	27	—	—	133	—	μH	Circuit inductance required to limit di/dt

Table 3. Single Event Effects ⑨

Parameter	Typ.	Units	Ion	LET (Si) (MeV/mg/cm ²)	Fluence (ions/cm ²)	Range (μm)	V_{DS} Bias (V)	V_{GS} Bias (V)
BV_{DSS}	500	V	Ni	28	1×10^5	~35	400	-5

- ## Case Outline and Dimensions — TO-259AA



BERYLLIA WARNING PER MIL-PRF-19500

Packages containing beryllia shall not be ground, sandblasted, machined, or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxides packages shall not be placed in acids that will produce fumes containing beryllium.

International IOR Rectifier

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Data and specifications subject to change without notice.

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